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(54) **MICRO LED STRUCTURE AND MICRO LED PANEL**

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(57) **ABSTRACT**

A micro LED structure and a full color micro LED panel are provided by the disclosure. The micro LED structure comprises an IC back plane, at least three mesa structures stacked along a vertical axis, and a top contact formed above the at least three mesa structures. The second mesa structure comprises a first connecting layer, a first reflection layer formed on the first connecting layer, a first bonding layer formed on the first reflection layer, a first light emitting layer formed on the first bonding layer, and a second connecting layer formed on the first light emitting layer. The third mesa structure comprises a second reflection layer formed on the second connecting layer, a second bonding layer formed on the second reflection layer, a second light emitting layer formed on the second bonding layer, and a third connecting layer formed on the second light emitting layer.

